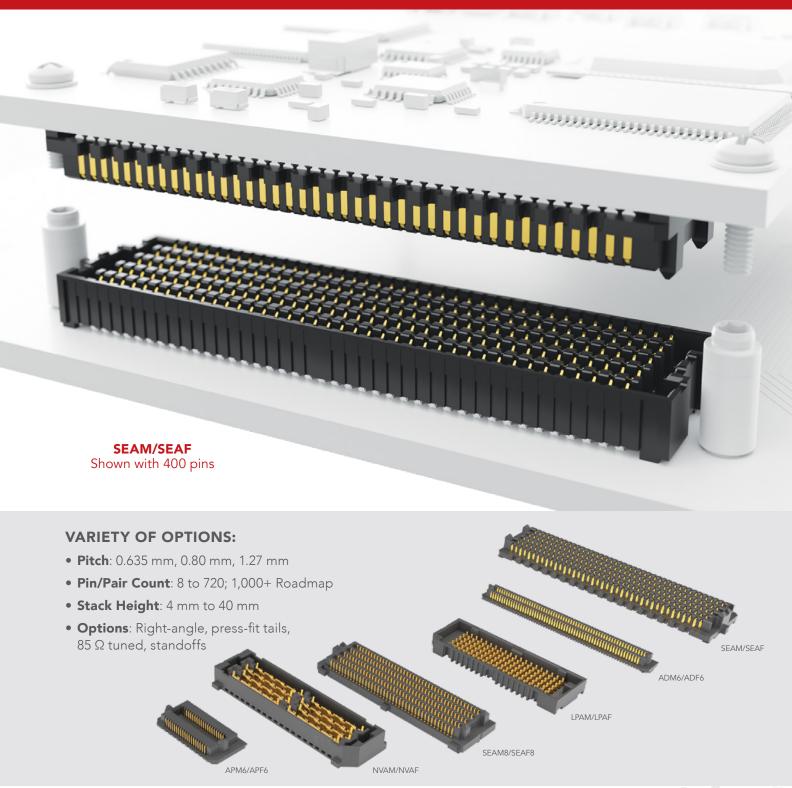


HIGH-DENSITY ARRAYS

EXTREME PERFORMANCE • OPEN-PIN-FIELD • LOW-PROFILE



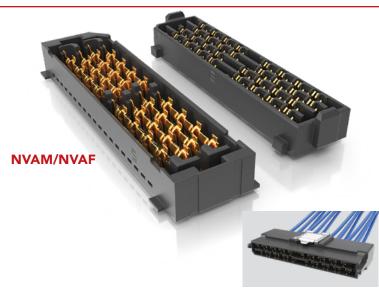
EXTREME PERFORMANCE ARRAYS

- 4.0 Tbps aggregate data rate 9 IEEE 400G channels
- Two points of contact ensure a more reliable connection
- Fully shielded differential pair design
- Extremely low crosstalk (to 40 GHz) and incredibly tight impedance control
- Minimal variance in data rate as stack height increases
- Utilizes 40% less space with the same data throughput as compared to traditional arrays
- Terminal with latching available to mate with NovaRay® cable (NVAM-C)









Mating assembly with 34 AWG Eye Speed® ultra low skew twinax cable

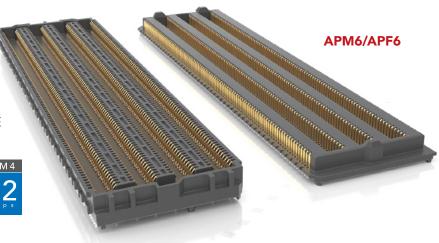
HIGH-PERFORMANCE ARRAYS

- Flexible open-pin-field and cost optimized, extreme performance solution
- Low-profile 5 mm stack height and up to 10 mm
- 0.635 mm pitch
- Four row design with up to 400 total pins; roadmap to 1,000+ pins
- Data rate compatible with PCle® Gen 5 and 100 GbE
- Cable assembly in development









HIGH-DENSITY ARRAYS

- Up to 400 I/Os in a 4-row design
- Open-pin-field design for grounding and routing flexibility
- 0.635 mm pitch Edge Rate® contacts
- Low profile 5 mm stack height and slim 5 mm width
- Other stack heights in development



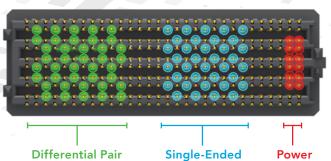




1.27 mm PITCH ARRAYS

- Maximum grounding and routing flexibility
- Up to 560 Edge Rate® contacts optimized for signal integrity performance
- 7 mm to 40 mm stack heights; right-angle available
- Supports high-speed protocols such as Ethernet, PCI Express®, Fibre Channel and InfiniBand™

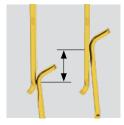
OPEN-PIN-FIELD FLEXIBILITY











1.12 mm (.044") contact wipe



Solder charge terminations (IPC-A-610F & IPC J-STD-001F Class 3)



Elevated stack heights available (SEAR)



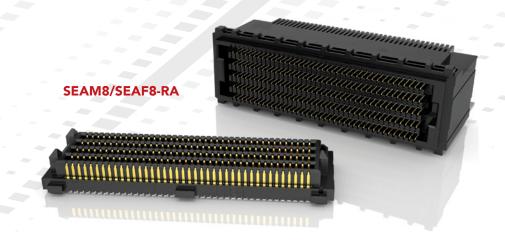
Press-fit tails available (SEAMP/SEAFP)



Jack screw standoffs (JSO)

HIGH-DENSITY 0.80 mm PITCH ARRAYS

- 2x the density of 1.27 mm pitch arrays
- Up to 720 Edge Rate® contacts; higher pin counts in development
- 7 mm and 10 mm stack heights
- 2 mm extended wipe in development
- Jack screw standoffs available (JSO)



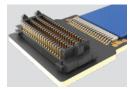








Lead-free solder charge terminations



Mating assembly with 34 AWG micro ribbon coax cable (ESCA)

LOW PROFILE ARRAYS

- Up to 400 total pins in 4, 6 or 8 rows
- 4 mm, 4.5 mm and 5 mm stack heights
- 1.27 mm pitch
- Solder crimped termination for ease of processing
- Press-in or threaded standoffs available assist with unmating (JSO)











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